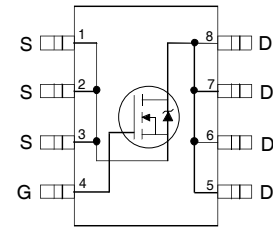


**Applications**

- Synchronous MOSFET for Notebook Processor Power
- Synchronous Rectifier MOSFET for Isolated DC-DC Converters in Networking Systems



Top View

**Benefits**

- Very Low  $R_{DS(on)}$  at 4.5V  $V_{GS}$
- Low Gate Charge
- Fully Characterized Avalanche Voltage and Current  
100% Tested for  $R_G$
- Lead -Free
- $V_{DS(V)} = 30V$
- $I_D = -18A$  ( $V_{GS} = 10V$ )
- $R_{DS(ON)} < 4.8m\Omega$  ( $V_{GS}=10V$ )
- $R_{DS(ON)} < 6.8m\Omega$  ( $V_{GS}=4.5V$ )

**Absolute Maximum Ratings**

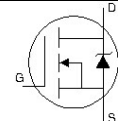
	Parameter	Max.	Units
$V_{DS}$	Drain-to-Source Voltage	30	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	18	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	14.4	
$I_{DM}$	Pulsed Drain Current ①	144	
$P_D @ T_A = 25^\circ C$	Power Dissipation ④	2.5	W
$P_D @ T_A = 70^\circ C$	Power Dissipation ④	1.6	
	Linear Derating Factor	0.02	W/ $^\circ C$
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to + 150	$^\circ C$

**Thermal Resistance**

	Parameter	Typ.	Max.	Units
$R_{\theta JL}$	Junction-to-Drain Lead ⑤		20	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient ④⑤		50	

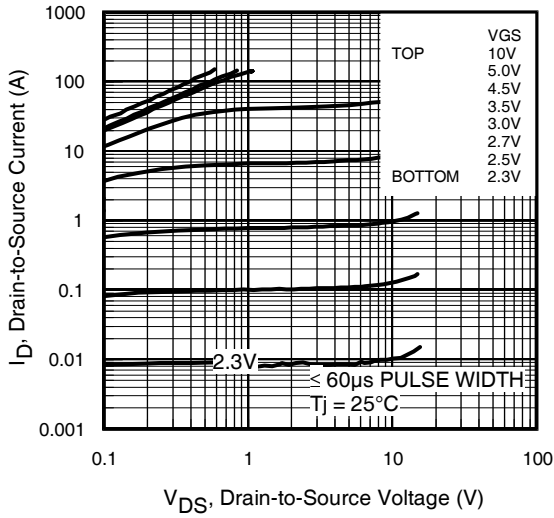
**Static @ T<sub>J</sub> = 25°C (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	30			V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temp. Coefficient		0.022		V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance		3.9	4.8	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 18A ③
			5.5	6.8		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 14.4A ③
V <sub>GS(th)</sub>	Gate Threshold Voltage	1.35	1.8	2.35	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 50μA
ΔV <sub>GS(th)</sub>	Gate Threshold Voltage Coefficient		-6.1		mV/°C	
I <sub>DSS</sub>	Drain-to-Source Leakage Current			1.0	μA	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V
				150		V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	nA	V <sub>GS</sub> = 20V
	Gate-to-Source Reverse Leakage			-100		V <sub>GS</sub> = -20V
g <sub>fs</sub>	Forward Transconductance	52			S	V <sub>DS</sub> = 15V, I <sub>D</sub> = 14.4A
Q <sub>g</sub>	Total Gate Charge		17	26	nC	V <sub>DS</sub> = 15V V <sub>GS</sub> = 4.5V I <sub>D</sub> = 14.4A See Fig. 16
Q <sub>gs1</sub>	Pre-V <sub>th</sub> Gate-to-Source Charge		4.4			
Q <sub>gs2</sub>	Post-V <sub>th</sub> Gate-to-Source Charge		1.9			
Q <sub>gd</sub>	Gate-to-Drain Charge		5.8			
Q <sub>godr</sub>	Gate Charge Overdrive		4.9			
Q <sub>sw</sub>	Switch Charge (Q <sub>gs2</sub> + Q <sub>gd</sub> )		7.7			
Q <sub>oss</sub>	Output Charge		7.1		nC	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V
R <sub>G</sub>	Gate Resistance		1.3	2.2	Ω	
t <sub>d(on)</sub>	Turn-On Delay Time		12		ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 4.5V ③ I <sub>D</sub> = 14.4A R <sub>G</sub> = 1.8Ω See Fig. 14
t <sub>r</sub>	Rise Time		15			
t <sub>d(off)</sub>	Turn-Off Delay Time		13			
t <sub>f</sub>	Fall Time		7.5			
C <sub>iss</sub>	Input Capacitance		2315		pF	V <sub>GS</sub> = 0V V <sub>DS</sub> = 15V f = 1.0MHz
C <sub>oss</sub>	Output Capacitance		449			
C <sub>rss</sub>	Reverse Transfer Capacitance		219			
I <sub>S</sub>	Continuous Source Current (Body Diode)			3.1	A	MOSFET symbol showing the integral reverse p-n junction diode.
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①			144		
V <sub>SD</sub>	Diode Forward Voltage			1.0	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 14.4A, V <sub>GS</sub> = 0V ③
t <sub>rr</sub>	Reverse Recovery Time		16	24	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 14.4A, V <sub>DD</sub> = 10V
Q <sub>rr</sub>	Reverse Recovery Charge		19	29	nC	di/dt = 300A/μs ③
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

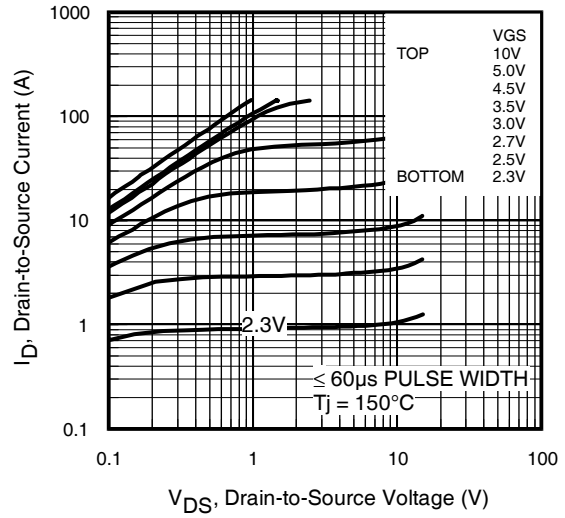


**Avalanche Characteristics**

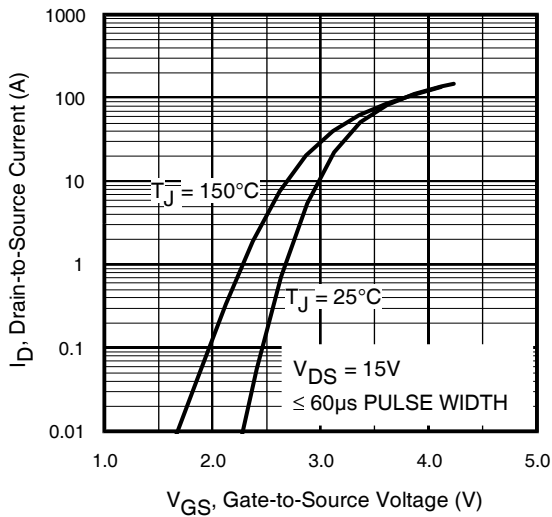
	Parameter	Typ.	Max.	Units
E <sub>AS</sub>	Single Pulse Avalanche Energy ②		126	mJ
I <sub>AR</sub>	Avalanche Current ①		14.4	A



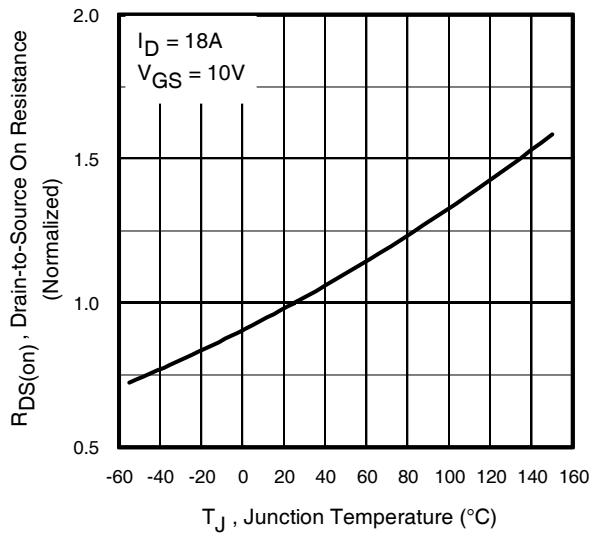
**Fig 1.** Typical Output Characteristics



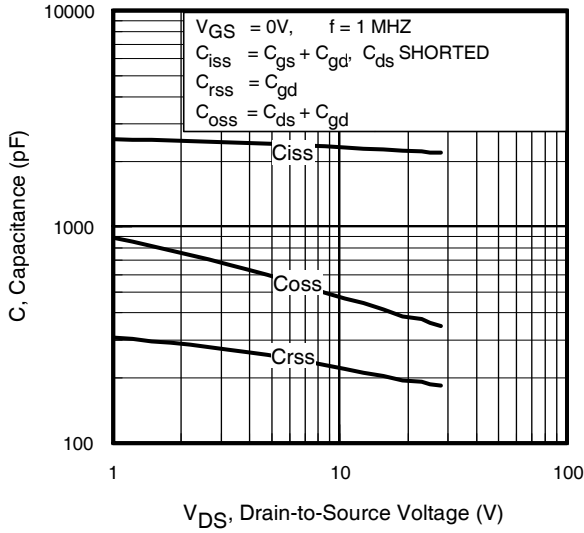
**Fig 2.** Typical Output Characteristics



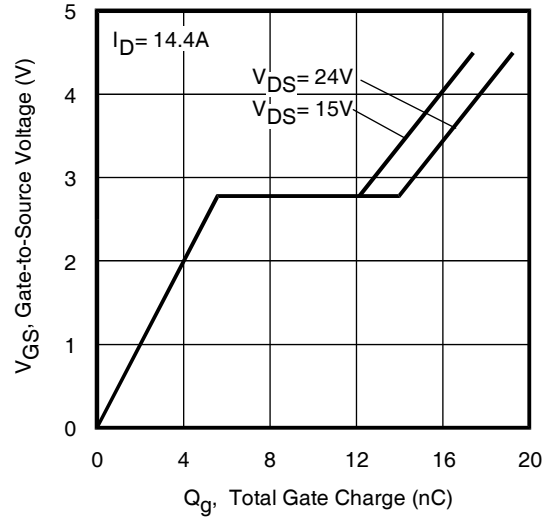
**Fig 3.** Typical Transfer Characteristics



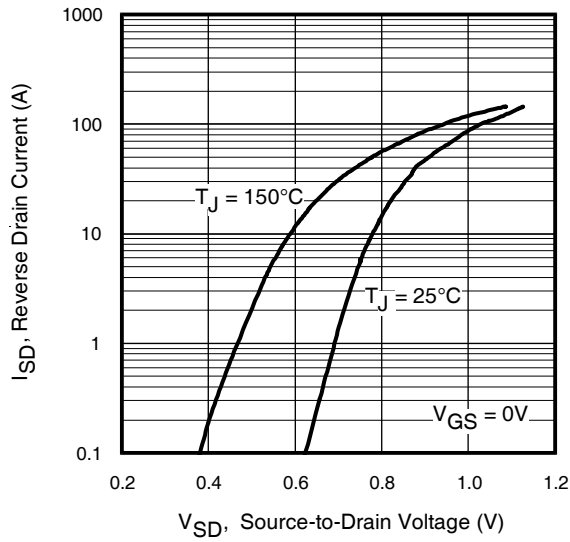
**Fig 4.** Normalized On-Resistance Vs. Temperature



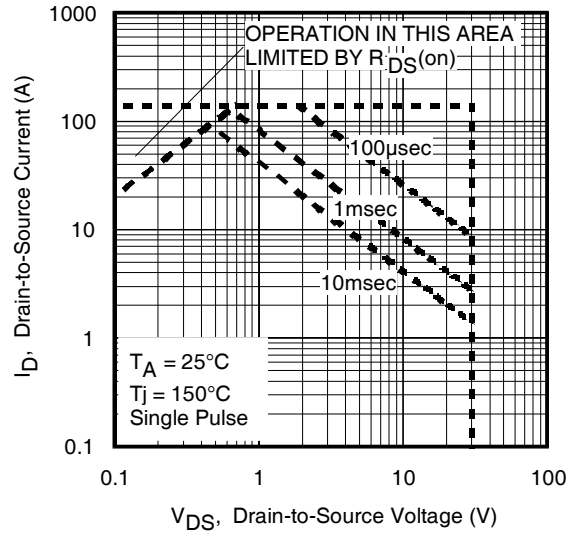
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



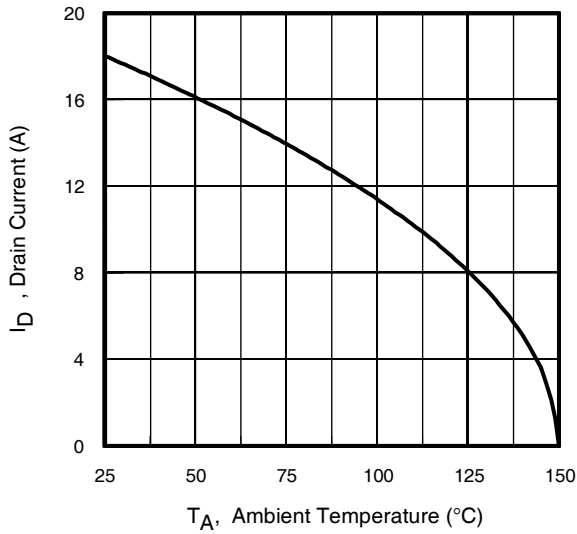
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



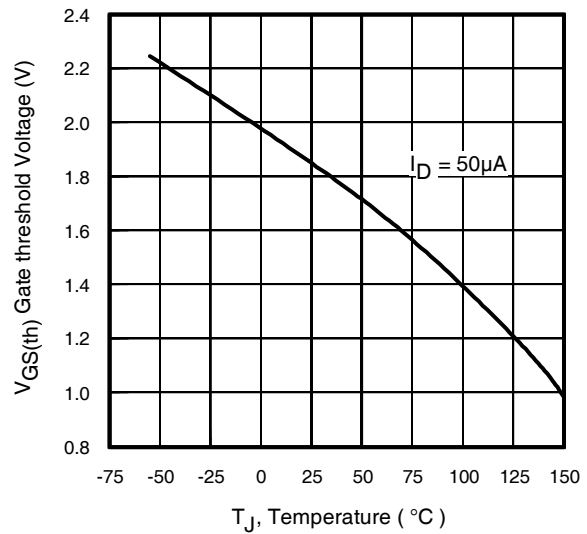
**Fig 7.** Typical Source-Drain Diode Forward Voltage



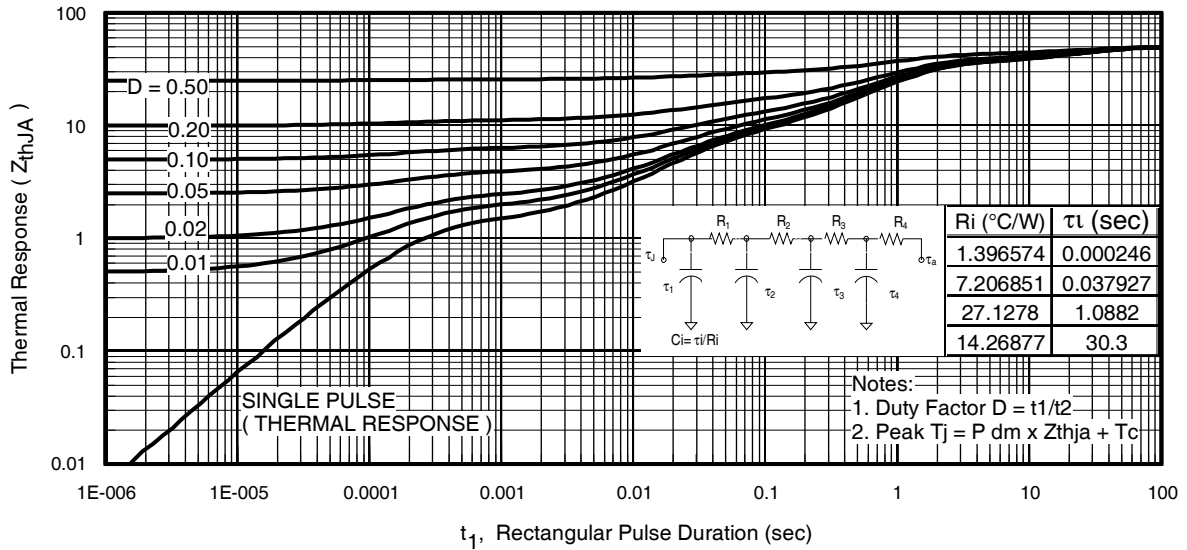
**Fig 8.** Maximum Safe Operating Area



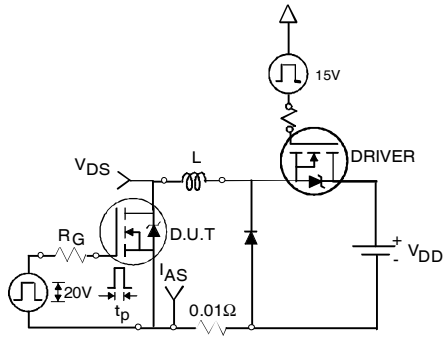
**Fig 9.** Maximum Drain Current Vs. Ambient Temperature



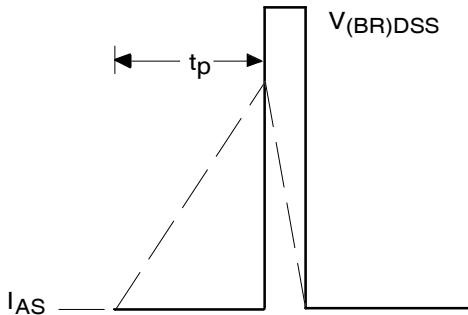
**Fig 10.** Threshold Voltage Vs. Temperature



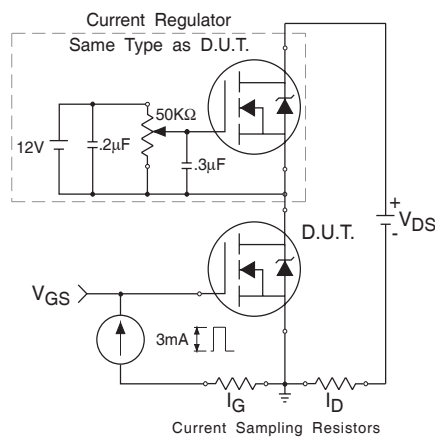
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



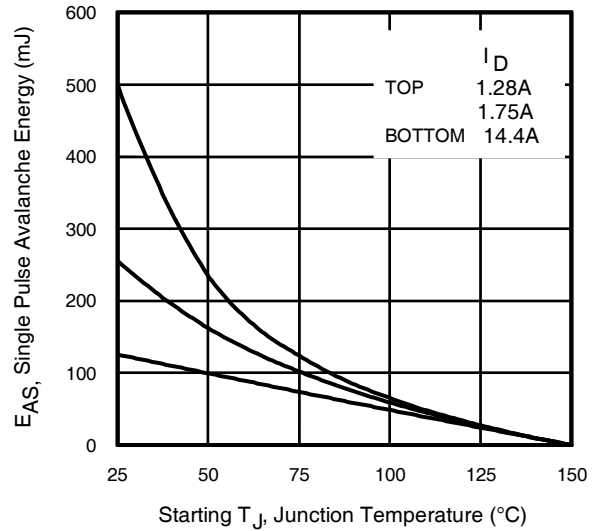
**Fig 12a.** Unclamped Inductive Test Circuit



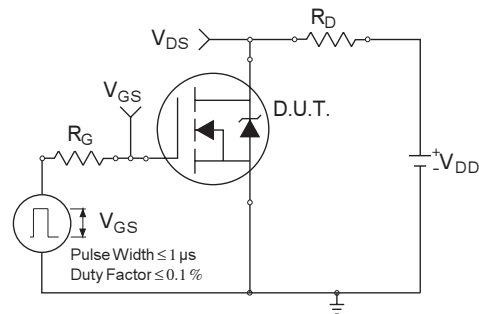
**Fig 12b.** Unclamped Inductive Waveforms



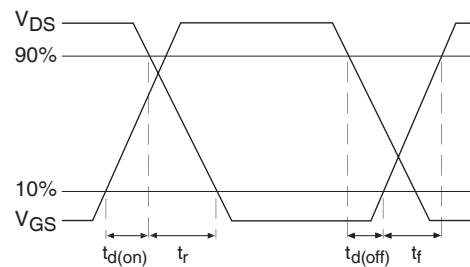
**Fig 13.** Gate Charge Test Circuit



**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



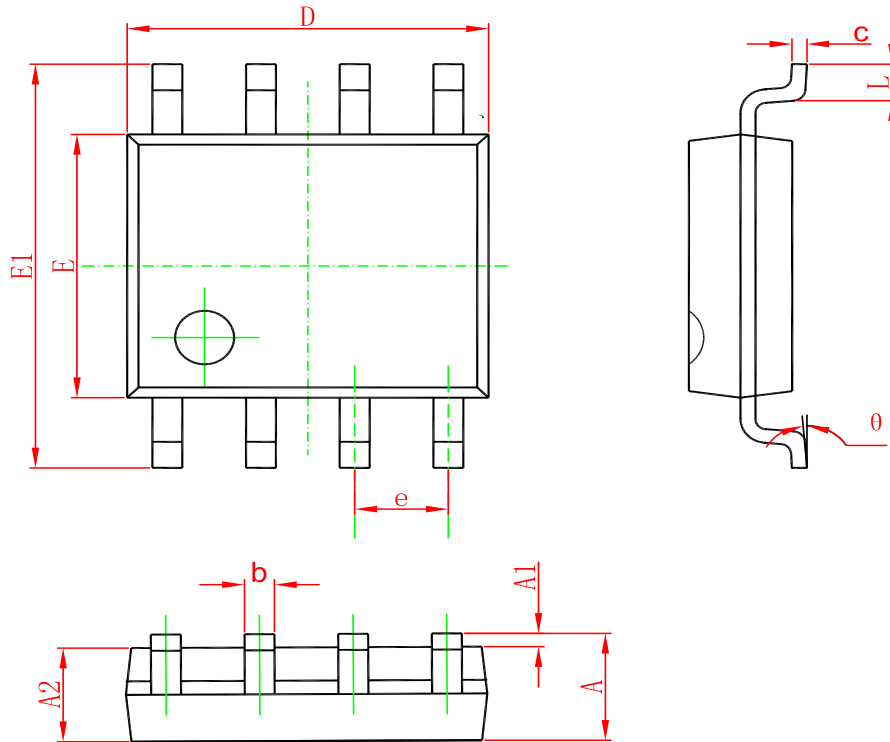
**Fig 14a.** Switching Time Test Circuit



**Fig 14b.** Switching Time Waveforms

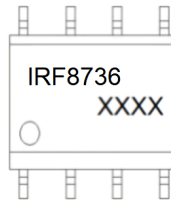
**PACKAGE OUTLINE DIMENSIONS**

**SOP-8**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

## Marking



## Ordering information

Order code	Package	Baseqty	Deliverymode
IRF8736	SOP-8	3000	Tape and reel